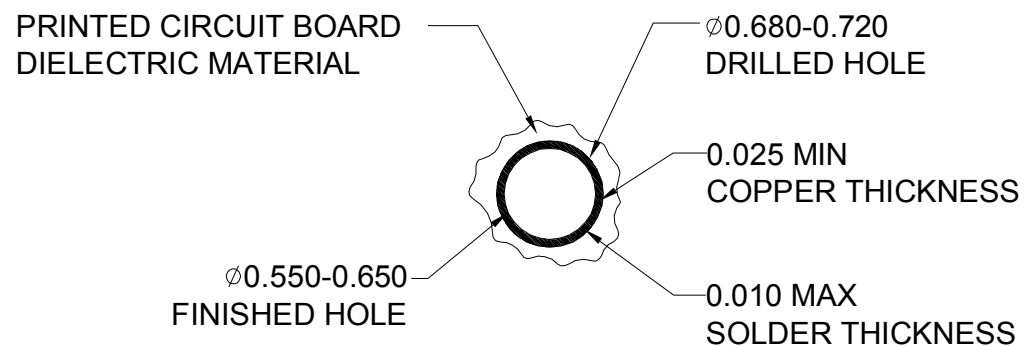
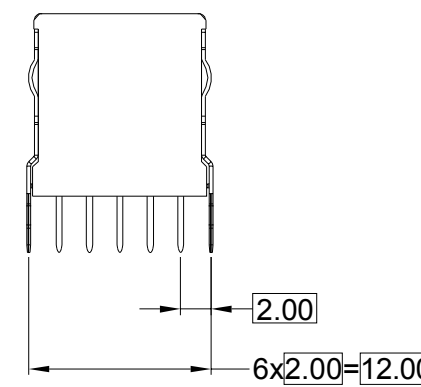
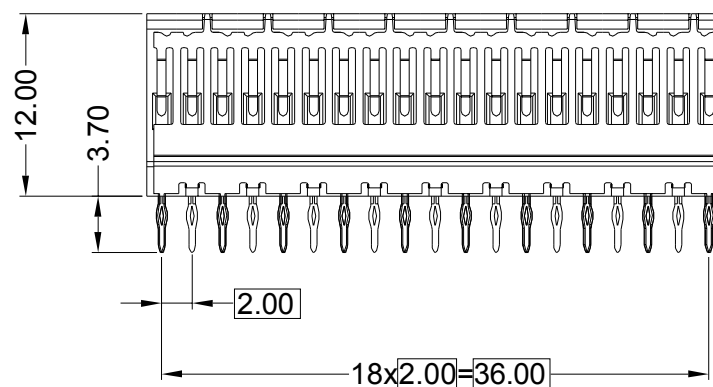
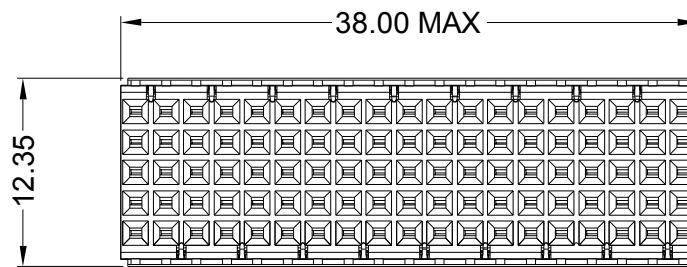
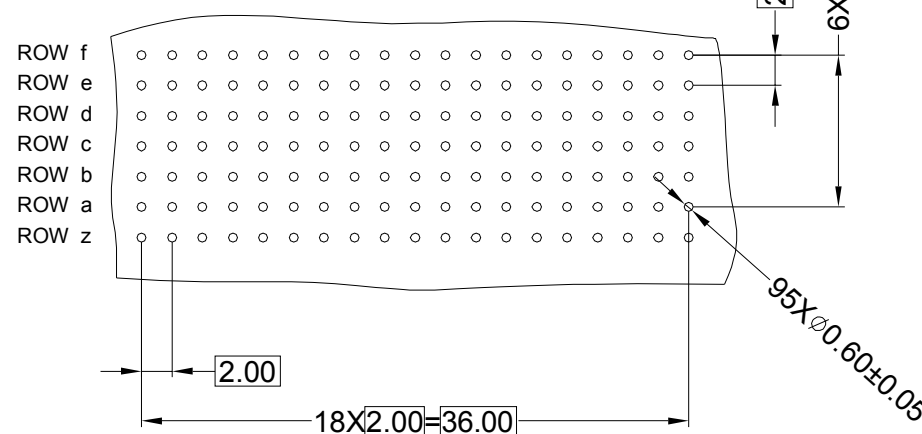


**NOTES:**

1. ALL DIMENSION ARE IN mm.
2. MATERIAL:  
HOUSING: THERMOPLASTIC(94V-0) COLOR: GRAY  
CONTACT: COPPER ALLOY
3. FINISH:  
CONTACT AREA: GOLD PLATING;  
PRESS FIT AREA: MATTE TIN PLATING.
4. ENGAGING AND SEPARATING FORCES PER IEC 61076-4-101.
5. ROHS DIRECTIVE COMPLIANCE.
6. MAX SOLDERING TEMPERATURE 225°C.
7. PERFORMANCE CHARACTERISTICS  
INSULATION RESISTANCE: 10,000 MEGOHMS MINIMUM  
DIELECTRIC WITHSTANDING VOLTAGE(AT SEA LEVEL): 750 Vrms  
CURRENT RATING: 1 AMP AT 70°C, FULLY LOADED  
1.5 AMP AT 20°C, FULLY LOADED  
OPERATING TEMPERATURE RANGE: -55°C TO +125°C  
CONTACT RESISTANCE: 20 MILLIOHMS MAXIMUM



THRU HOLE PLATING  
SCALE 10:1



PCB LAYOUT

DESIGN UNITS ■ mm □ INCH		NAME: 2MM 180° SOCKET B19 TYPE WITH SHIELD	<b>nexttron</b> NEXTRONICS ENGINEERING CORP.	
GENERAL TOLERANCES: (UNLESS SPECIFIED)		PART NO: NX7B0AE01A2AF	TITLE: CUSTOMER DWG	C
	mm	INCH	DWG. NO: 010-0000-856-NX7B0AE01A2AF	
4 PLACE	±.**	±.**	SCALE: 1/1	
3 PLACE	±.**	±.**	SHEET: 1/1	
2 PLACE	±0.20	±.**	REV.: X1	
1 PLACE	±0.30	±.**		
ANGULAR:	X°±.**	.X°±.**		
APPD: 楊海文 5/20'11	CHKD: 楊海文 5/20'11	DRAWN: 廖小瓊 5/20'11		

X1	***	New Release	5/20'11	廖小瓊	楊海文
REV.	ECN. NO.	DESCRIPTION	DATE	DRAWN	APPD